

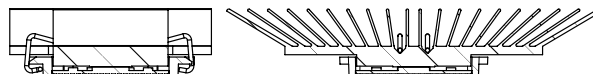
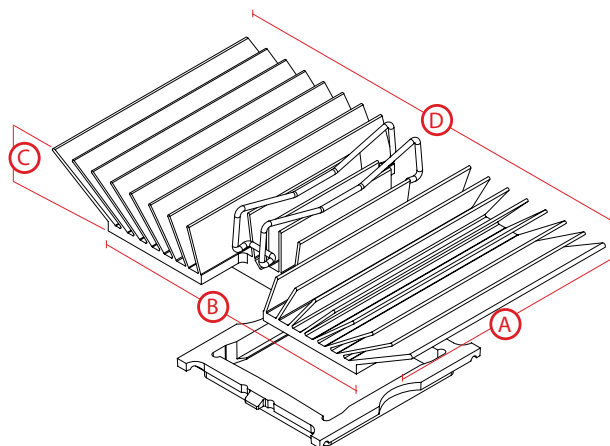


Custom High Performance Cooling Solutions w/ maxiGRIP™ Attachment

ATS PART # ATS-59008-C2-R0

Features & Benefits

- » Designed for flip-chip processors such as Freescale MPCs
- » maxiGRIP™ attachment applies steady, even pressure to the component and does not require holes in the PCB
- » Comes preassembled with high performance, phase changing, thermal interface material



**Image above is for illustration purposes only.*

Thermal Performance

AIR VELOCITY

FT/MIN

M/S

THERMAL RESISTANCE

°C/W (UNDUCTED FLOW)

°C/W (DUCTED FLOW)

200

1.0

2.42

1.6

300

1.5

1.98

400

2.0

1.7

500

2.5

1.53

600

3.0

1.4

700

3.5

1.3

800

4.0

1.2

Product Details

DIMENSION A

DIMENSION B

DIMENSION C

DIMENSION D

INTERFACE MATERIAL

FINISH

35 mm

46 mm

16 mm

57.8 mm

SAINT-GOBAIN C1100F

BLACK-ANODIZED

NOTES:

- 1) Dimension C = heat sink height from bottom of the base to the top of the fin field.
- 2) ATS-59008-C1-R0 is a substitute item available utilizing an equivalent phase change material (Chomerics T766).
- 3) Thermal performance data are provided for reference only. Actual performance may vary by application.
- 4) ATS reserves the right to update or change its products without notice to improve the design or performance.
- 5) Contact ATS to learn about custom options available.



ATS ADVANCED THERMAL SOLUTIONS, INC.
Innovations in Thermal Management®

For more information, to find a distributor or to place an order, visit www.qats.com or call: 781.769.2800 (North America); +31 (0) 3569 84715 (Europe).